



SamHop Microelectronics Corp.



STU/D413S

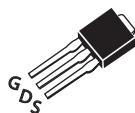
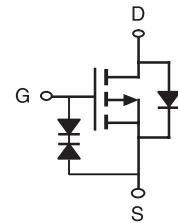
Ver 1.1

## P-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Max
-40V	-22A	48 @ VGS=10V
		78 @ VGS=4.5V

### FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- Surface Mount Package.
- ESD Protected.

STU SERIES  
TO-252AA(D-PAK)STD SERIES  
TO-251(I-PAK)

### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Limit	Units
$V_{DS}$	Drain-Source Voltage		-40	V
$V_{GS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Drain Current-Continuous	$T_C=25^\circ\text{C}$	-22	A
		$T_C=70^\circ\text{C}$	-17.6	A
$I_{DM}$	-Pulsed <sup>a</sup>		-66	A
$E_{AS}$	Sigle Pulse Avalanche Energy <sup>c</sup>		16	mJ
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	42	W
		$T_C=70^\circ\text{C}$	27	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range		-55 to 150	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	$^\circ\text{C/W}$

Details are subject to change without notice.

Aug,24,2012

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## ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}=-32\text{V}$ , $V_{GS}=0\text{V}$			1	$\mu\text{A}$
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}$ , $V_{DS}=0\text{V}$			$\pm 10$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-1	-1.8	-3	V
R <sub>D(S(ON))</sub>	Drain-Source On-State Resistance	$V_{GS}=-10\text{V}$ , $I_D=-11\text{A}$		38	48	m ohm
		$V_{GS}=-4.5\text{V}$ , $I_D=-8.6\text{A}$		58	78	m ohm
$g_{FS}$	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-11\text{A}$		10		S
<b>DYNAMIC CHARACTERISTICS</b> <sup>b</sup>						
C <sub>iss</sub>	Input Capacitance	$V_{DS}=-20\text{V}$ , $V_{GS}=0\text{V}$ $f=1.0\text{MHz}$		895		pF
C <sub>oss</sub>	Output Capacitance			138		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			67		pF
<b>SWITCHING CHARACTERISTICS</b> <sup>b</sup>						
t <sub>D(ON)</sub>	Turn-On Delay Time	$V_{DD}=-20\text{V}$ $I_D=-1.0\text{A}$ $V_{GS}=-10\text{V}$ $R_{GEN}=3.3\text{ ohm}$		14		ns
t <sub>r</sub>	Rise Time			14		ns
t <sub>D(OFF)</sub>	Turn-Off Delay Time			54		ns
t <sub>f</sub>	Fall Time			10		ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS}=-20\text{V}$ , $I_D=-11\text{A}$ , $V_{GS}=-10\text{V}$		14.5		nC
		$V_{DS}=-20\text{V}$ , $I_D=-11\text{A}$ , $V_{GS}=-4.5\text{V}$		7		nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}=-20\text{V}$ , $I_D=-11\text{A}$ , $V_{GS}=-10\text{V}$		2.1		nC
Q <sub>gd</sub>	Gate-Drain Charge			3.4		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
V <sub>SD</sub>	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s = -2.0\text{A}$		-0.77	-1.3	V
<b>Notes</b>						
a.Pulse Test:Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$ .						
b.Guaranteed by design, not subject to production testing.						
c.Starting $T_j=25^\circ\text{C}$ , $L=0.5\text{mH}$ , $V_{DD} = 20\text{V}$ .(See Figure13)						

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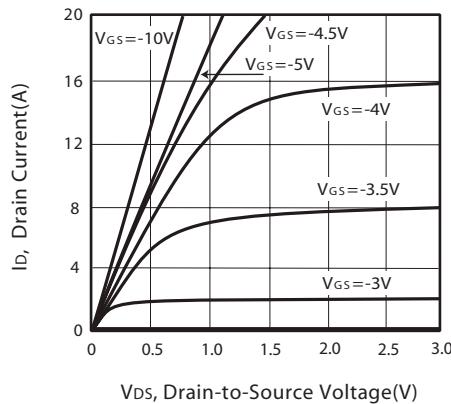


Figure 1. Output Characteristics

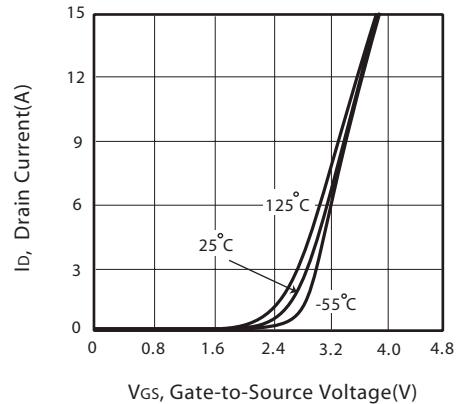


Figure 2. Transfer Characteristics

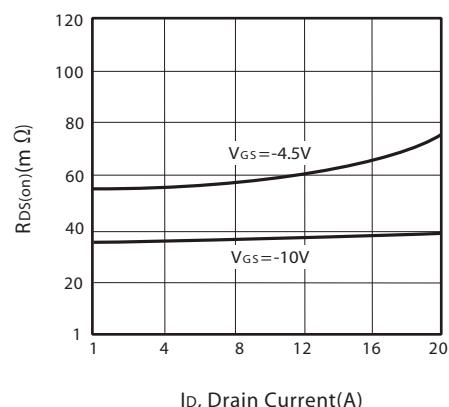


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

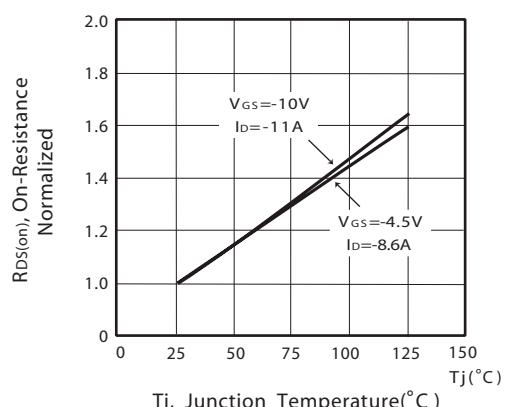


Figure 4. On-Resistance Variation with Drain Current and Temperature

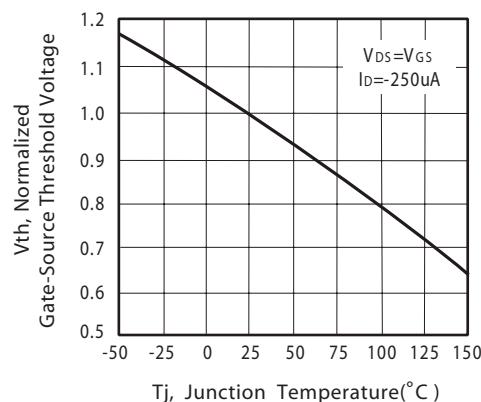


Figure 5. Gate Threshold Variation with Temperature

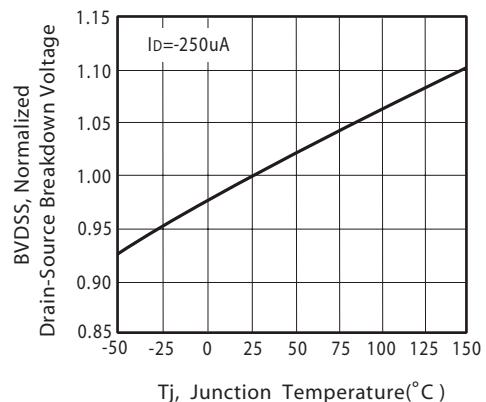
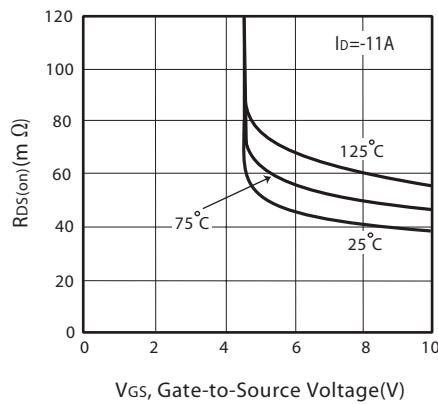
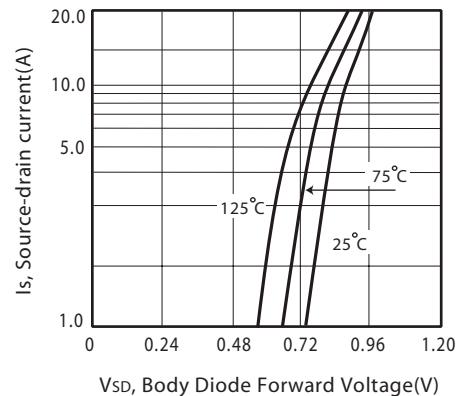


Figure 6. Breakdown Voltage Variation with Temperature



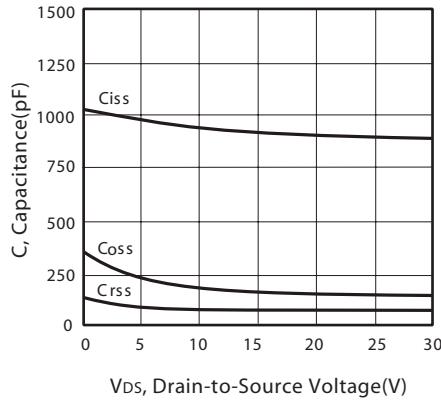
V<sub>GS</sub>, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



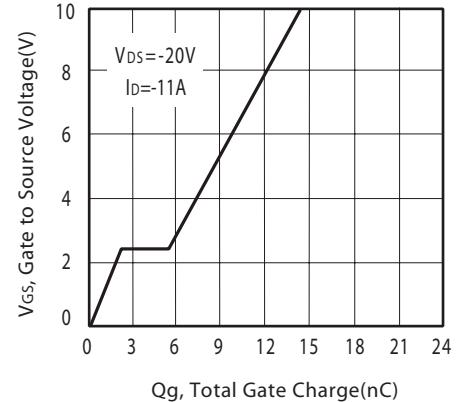
V<sub>SD</sub>, Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



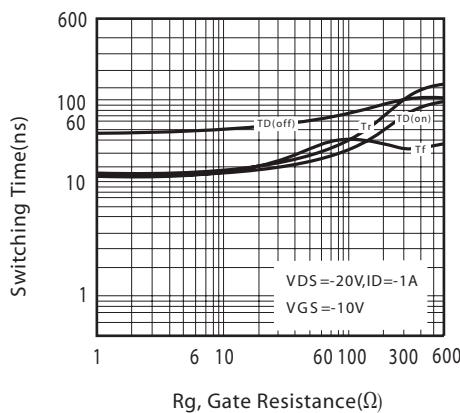
V<sub>DS</sub>, Drain-to-Source Voltage(V)

Figure 9. Capacitance



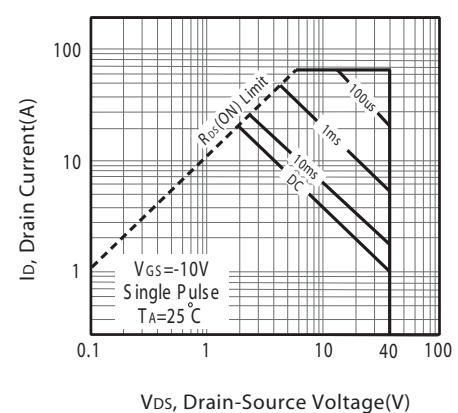
Q<sub>g</sub>, Total Gate Charge(nC)

Figure 10. Gate Charge



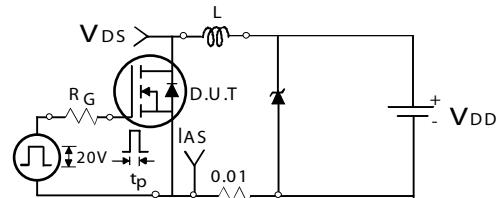
R<sub>g</sub>, Gate Resistance(Ω)

Figure 11. switching characteristics



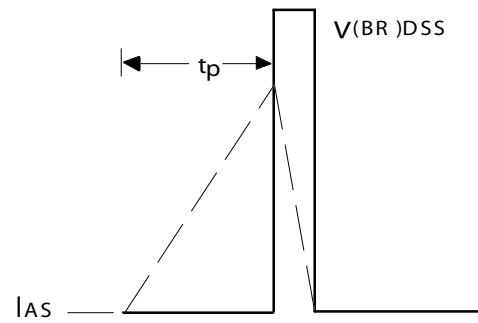
V<sub>DS</sub>, Drain-Source Voltage(V)

Figure 12. Maximum Safe Operating Area



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

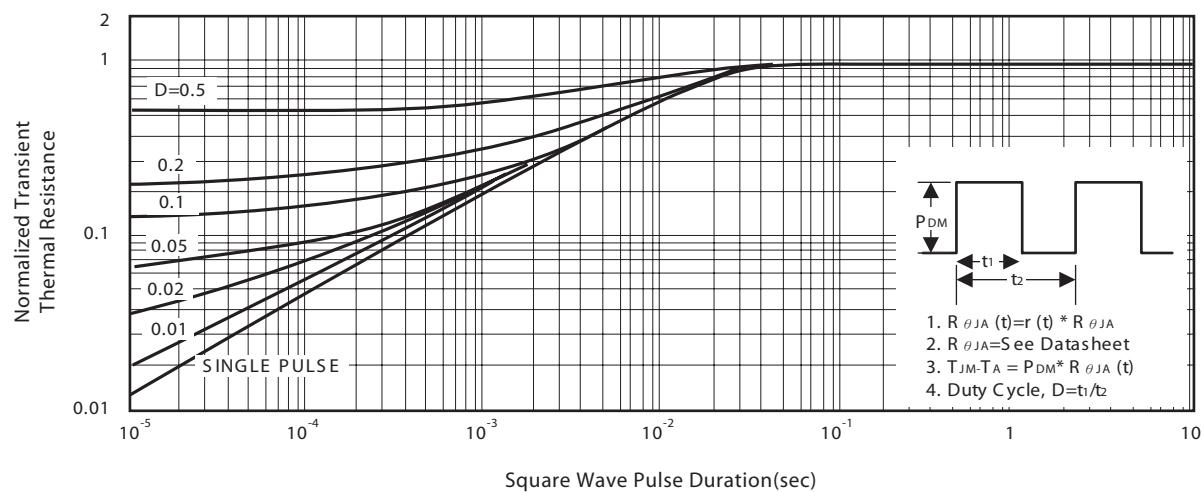


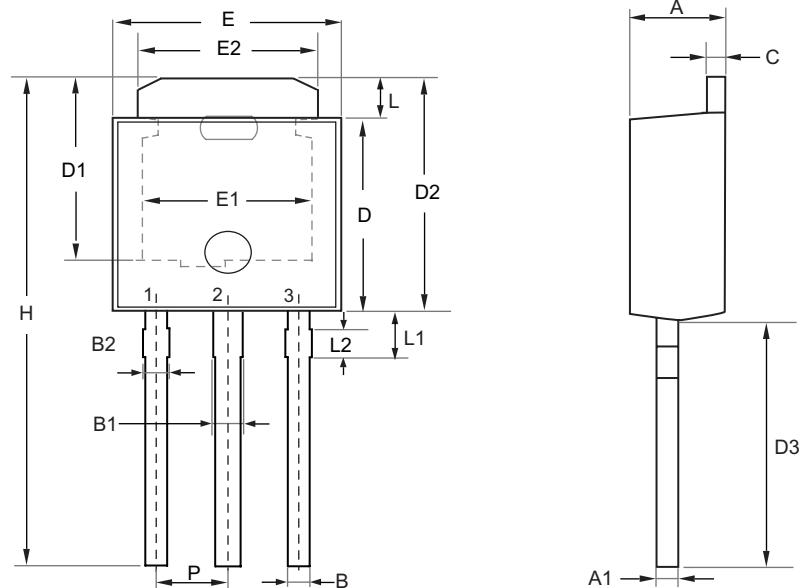
Figure 14. Normalized Thermal Transient Impedance Curve

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## PACKAGE OUTLINE DIMENSIONS

TO-251

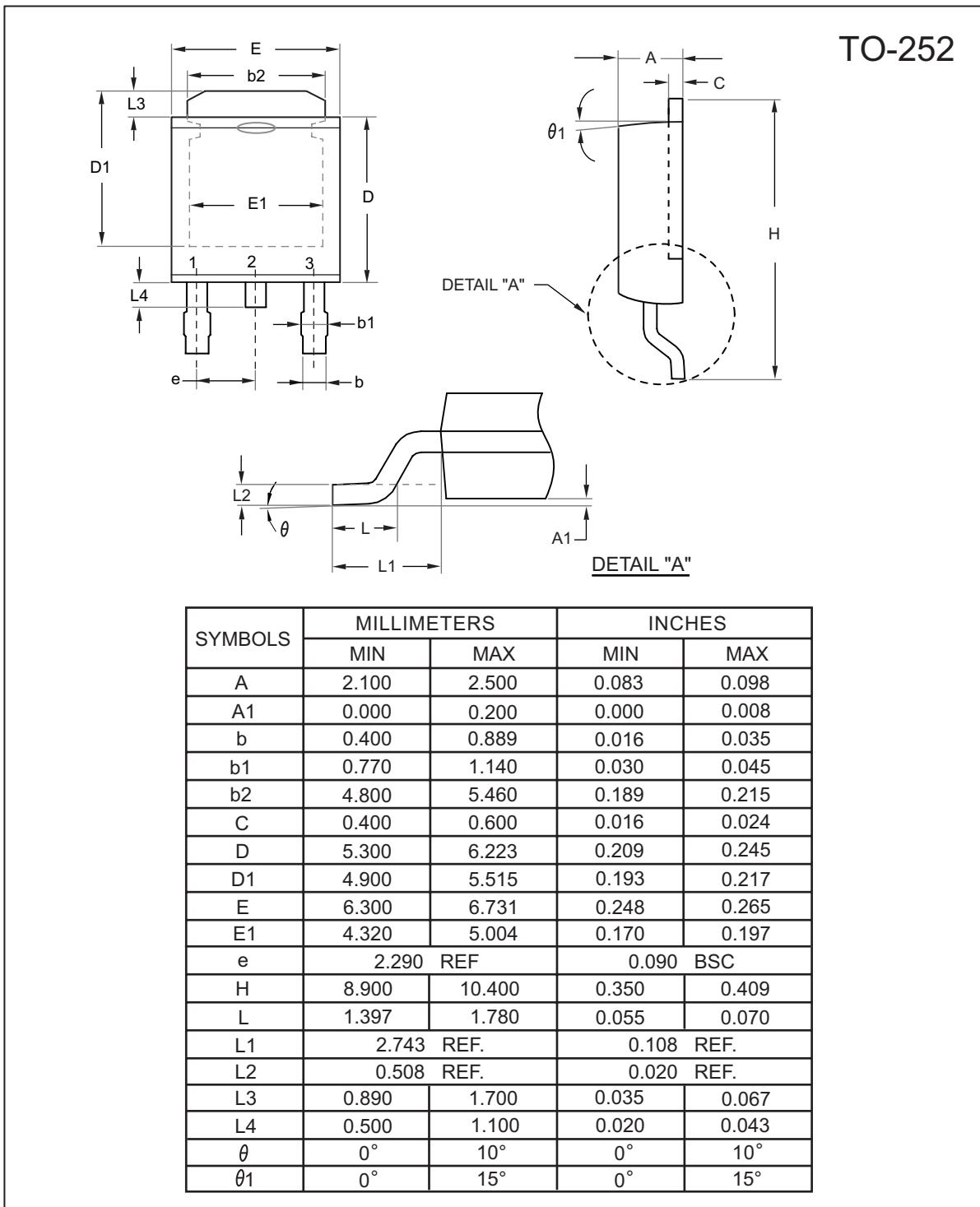


SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.100	2.500	0.083	0.098
A1	0.350	0.650	0.014	0.026
B	0.400	0.800	0.016	0.031
B1	0.650	1.050	0.026	0.041
B2	0.500	0.900	0.020	0.035
C	0.400	0.600	0.016	0.024
D	5.300	5.700	0.209	0.224
D1	4.900	5.300	0.193	0.209
D2	6.700	7.300	0.264	0.287
D3	7.000	8.000	0.276	0.315
H	13.700	15.300	0.539	0.602
E	6.300	6.700	0.248	0.264
E1	4.600	4.900	0.181	0.193
E2	4.800	5.200	0.189	0.205
L	1.300	1.700	0.051	0.067
L1	1.400	1.800	0.055	0.071
L2	0.500	0.900	0.020	0.035
P	2.300 BSC		0.091 BSC	

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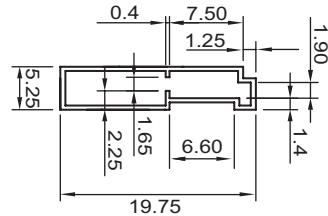
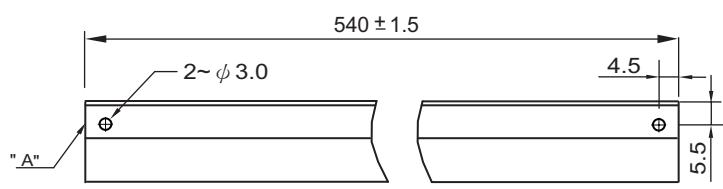


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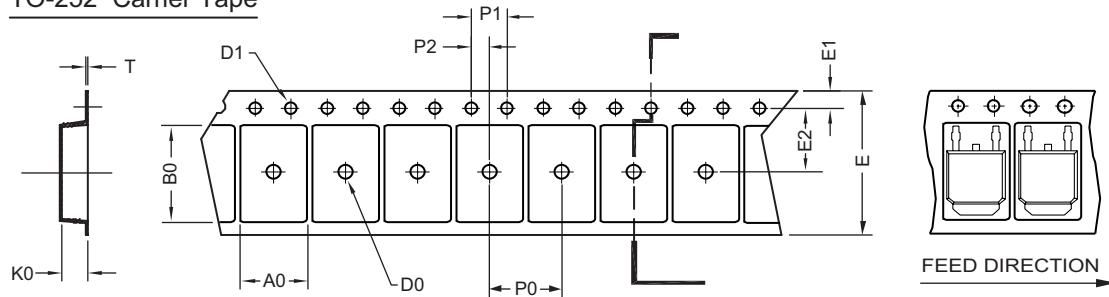
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## TO-251 Tube/TO-252 Tape and Reel Data

### TO-251 Tube



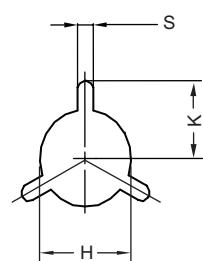
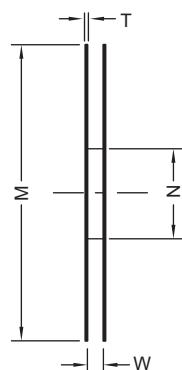
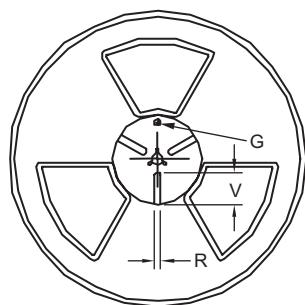
### TO-252 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
TO-252 (16 mm)	6.96 ±0.1	10.49 ±0.1	2.79 ±0.1	ψ 2	ψ 1.5 + 0.1 - 0	16.0 ±0.3	1.75 ±0.1	7.5 ±0.15	8.0 ±0.1	4.0 ±0.1	2.0 ±0.15	0.3 ±0.05

### TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	ψ 330	ψ 330 ± 0.5	ψ 97 ± 1.0	17.0 + 1.5 - 0	2.2	ψ 13.0 + 0.5 - 0.2	10.6	2.0 ± 0.5	---	---	---

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